

simple is better

MODEL 6200

AUTOMATIC DIE ATTACH SYSTEM



Performs **MCM, Flip Chip, Eutectic, Silver Glass, Ag Sintering** etc die attach applications.

Small footprint, **Table-Top** configuration.

Versatile and **User Friendly** machine using the same advanced software of Model 6400 running under Windows® on a PC platform.

Fully automatic and Semi-automatic process allowing highest flexibility and easy operation.

Very High Accuracy servo systems control the main machine axes.

High resolution **Digital Vision** and advanced **Image Processing** system.

Time-Pressure, Volumetric or **Jet Dispenser** for applying thermal or UV curing adhesives.

Double Dispenser for two different adhesives.

Stamping (Pin Transfer) 75 µm adhesive dots.

Die Presentation:

- Up to 10 Waffle/Gel packs 2".
- Up to 8 Tape & Reel feeders.
- Bulk and Other Feeders.
- Combinations of the above.

Unique one-pass, wet **Die Stacking** capability with **BLT control** of the dice.

Handles **MEMS, Sensors, Imaging Devices**, etc.

Multi-chip **Ag Sintering** using paste or Ag sheet.

Flip Chip, C2/C4 process including chip flipping, bump fluxing and final alignment over a high resolution Up Looking Camera.

Gold Bump Flip Chip based on Ultrasonic, Thermo-compression, ACF/ACP,

Eutectic MCM high temperature up to 500°C processes based on heated substrates and heated pickup tools, with provision of forming gas.

Specification Highlights

Work Area: up to 6" x 6".

Die size range: 0.006" to over 2"

Die Material: GaAs, Si, Glass, etc.

Substrates: Lead Frames, Ceramic, Silicon Wafers, PCB's, Metal, TO cans, etc.

Pickup/Bond Force: 40 to 9,000 grams.

Placement Accuracy: better than $\pm 3 \mu\text{m}$ - application dependent.

Throughput: up to 600 CPH - application dependent.

Size: 0.97 x 0.85 x 0.65 meter, table-top.

Weight: under 200 Kg.



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